

Listing of Claims:

The following listing of claims is provided for the convenience of the Examiner.
No amendments to the claims are made in this paper.

1. (Previously Presented) A movable microstructure comprising:
a first tiltable assembly formed over a substrate;
a second tiltable assembly formed over the substrate; and
first and second electrodes respectively positioned relative to the substrate to tilt
the first and second tiltable assemblies upon activation such that the first and second tiltable
assemblies are interdigitated.
2. (Original) The microstructure recited in claim 1 wherein the first tiltable
assembly is configured as a cantilever arrangement.
3. (Original) The microstructure recited in claim 2 wherein the second tiltable
assembly is configured as a torsion-beam arrangement.
4. (Original) The microstructure recited in claim 1 wherein the second tiltable
assembly is configured as a torsion-beam arrangement.
5. (Canceled).
6. (Previously Presented) The microstructure recited in claim 1,
wherein the first tiltable assembly includes:
a first structural linkage formed over the substrate;
a first structural film supported by the first structural linkage and having a
plurality of fingers at an end of the first structural film; and

wherein the second tilttable assembly includes:
a second structural linkage formed over the substrate; and
a second structural film supported by the second structural linkage and
having a plurality of fingers at an end of the second structural film.

7. (Original) The microstructure recited in claim 6 wherein the first and second electrodes comprise polysilicon.

8. (Original) The microstructure recited in claim 6 wherein the first and second structural films comprise polysilicon.

9. (Original) The microstructure recited in claim 6 wherein the first structural linkage has a greater height above the substrate than the second structural linkage.

10. (Previously Presented) A method for fabricating a movable microstructure, the method comprising:

forming a first tilttable assembly over a substrate;
forming a second tilttable assembly over the substrate; and
forming first and second electrodes relative to the substrate to tilt the first and second tilttable assemblies upon activation such that the first and second tilttable assemblies interdigitate.

11. (Original) The method recited in claim 10 wherein forming the first tilttable assembly comprises creating a cantilever arrangement.

12. (Original) The method recited in claim 11 wherein forming the second tilttable assembly comprises creating a torsion-beam arrangement.

13. (Original) The method recited in claim 10 wherein forming the second tilttable assembly comprises creating a torsion-beam arrangement.

14. (Canceled).

15. (Previously Presented) The method recited in claim 10, wherein forming the first tilttable assembly includes:

forming a first structural linkage over the substrate;

forming a first structural film on the first structural linkage, the first structural film having a plurality of fingers at an end of the first structural film; and

wherein forming the second tilttable assembly includes:

forming a second structural linkage over the substrate; and

forming a second structural film on the second structural linkage, the second structural film having a plurality of fingers at an end of the second structural film.

16. (Previously Presented) The method recited in claim 15 wherein forming the first structural linkage comprises forming the first structural linkage over the substrate at a height greater than the second structural linkage.

17. (Previously Presented) A method for operating a movable microstructure, the method comprising:

tilting a first assembly by applying a first electrostatic force, the first assembly including:

a first structural linkage formed over a substrate; and

a first structural film supported by the first structural linkage and having a plurality of fingers at an end of the first structural film;

tilting a second assembly by applying a second electrostatic force, the second assembly including:

a second structural linkage formed over the substrate; and

a second structural film supported by the second structural linkage and having a plurality of fingers at an end of the second structural film; and

holding the first and second assemblies electrostatically in a fixed position with the fingers of the first and second structural films interdigitated.

18. (Original) The method recited in claim 17 wherein the first assembly is configured as a cantilever arrangement.

19. (Original) The method recited in claim 18 wherein the second assembly is configured as a torsion-beam arrangement.

20. (Original) The method recited in claim 17 wherein the second assembly is configured as a torsion-beam arrangement.

21. (Canceled).

22. (Original) The method recited in claim 17 wherein tilting the first assembly comprises tilting the end of the first structural film having a plurality of fingers towards the substrate and tilting the second assembly comprises tilting the end of the second structural film having a plurality of fingers away from the structural assembly.

23. (Previously Presented) A movable microstructure, the microstructure comprising:

tiltable micromirror means formed over a support means;

tiltable snare means connected with the support means; and

means for generating electrostatic forces for tilting the tiltable micromirror means and the tiltable snare means into an interdigitated configuration.

Amdt. dated February 10, 2005

Reply to Office Action of January 13, 2005

24. (Original) The microstructure recited in claim 23 wherein the tilttable micromirror means comprises cantilever means.

25. (Original) The microstructure recited in claim 28 wherein the snare means comprises torsion-beam means.

26. (Original) The microstructure recited in claim 23 wherein the micromirror means comprises torsion-beam means.

27. – 29. (Canceled).